

Materials and Technologies for Si/SiGe Based Spin Qubits

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Spin Qubits Based on Si/SiGe

Highlights from the QUASAR Project 4

Advantages and Challenges

- long coherence times, CMOS manufacturable
- \rightarrow 6 qubits in 2022 (Qutech), 12 Qubits in 2024 (Intel)
- material properties influence qubit performance
- \rightarrow optimization is required

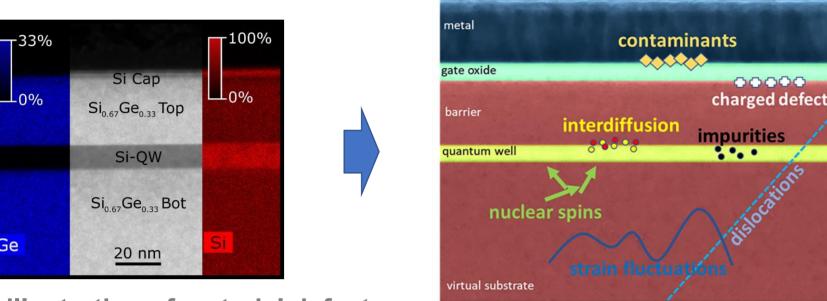


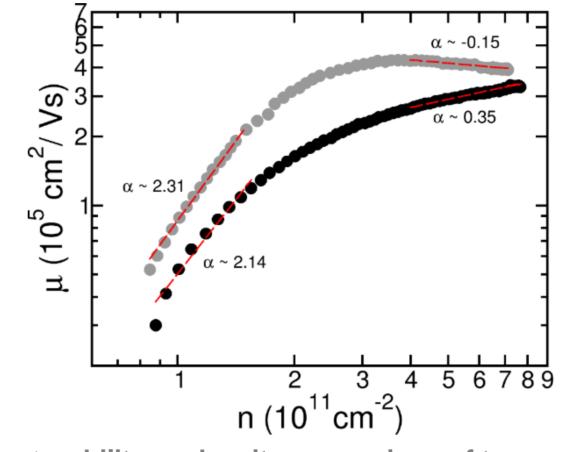
illustration of material defects -

Technology 200 mm / 300 mm 2

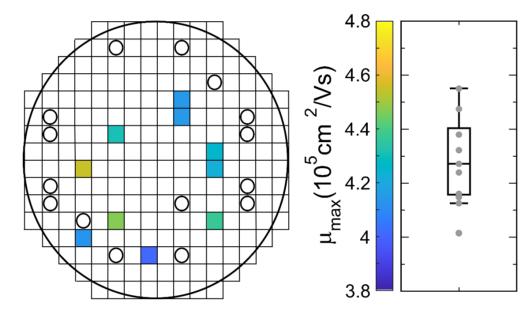
Growth, Fabrication & Components

- Si/SiGe heterostructures
- gate oxide based on PECVD, PVD and ALD
- gate based on PVD and CVD
- electron beam lithography for nanostructuring •
- test structures (HB-FETs, MOS dots)
- qubit templates, micromagnets

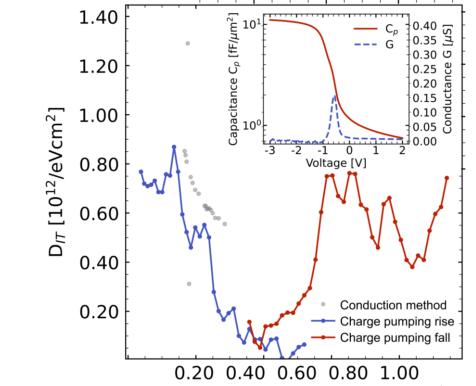
Characterization



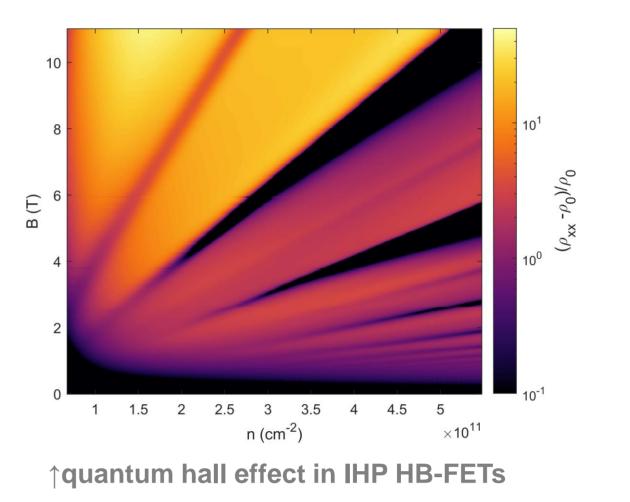
↑mobility vs density comparison of two wafers (grey optimized, black non-optimized)



↑wafer scale variation of maximum mobility



 E_T - E_V [eV]



Si/SiGe Technology for Qubits

- improved technology led to increased mobility https://doi.org/10.1149/11402.0109ecst https://doi.org/10.1149/11402.0123ecst
- maximum mobility of over 450,000 cm²/Vs
- percolation density at n = 0.7E11 cm⁻²
- variance of Hall bar parameters below 5%

Gate Oxide Quality

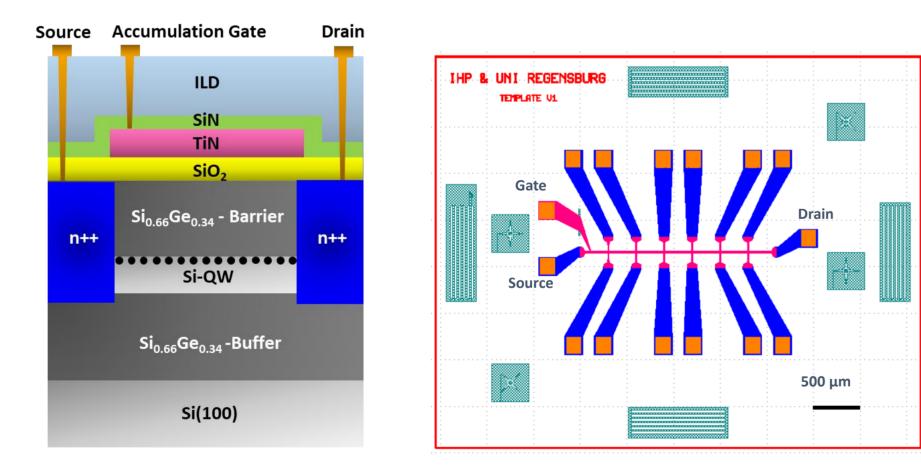
- energy-resolved defect density $D_{it} < 3E10$ cm⁻² eV⁻¹
- fixed charge concentration $Q_{fix} < 5E10 \text{ cm}^{-2}$
- determination of hysteresis, permittivity number • flicker Noise, Charge Pumping, Conduction Method (C/V, G/V)

- AFM, XRD, XRR, XPS, SEM, TEM, SIMS
- transport properties (1.5 K, 12 T)
- characterization of gate oxides

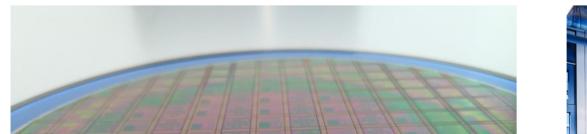
↑ measurement to extract oxide quality

https://doi.org/10.1063/5.0147586

Components for Si/SiGe Spin Qubits 3



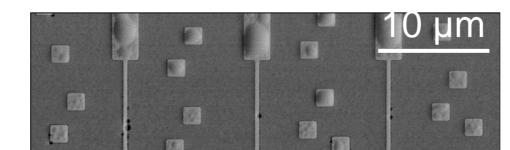
↑HB-FET technology at IHP







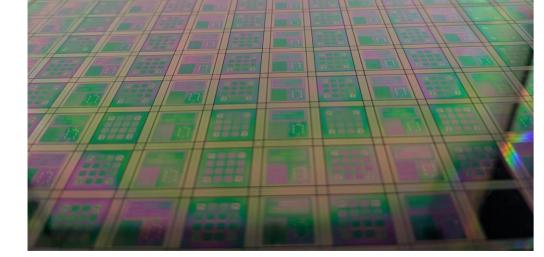
- Marker
- Ohmic contacts (implantation)
- Mesa Definition
- Gate oxide (SiO_2, HfO_2, Al_2O_3)
- Gate (TiN)
- Contact module
- Metal1
- Micromagnets



Summary 5

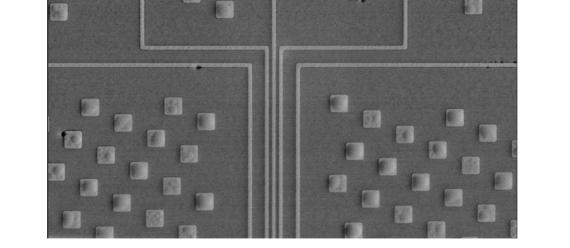
- production of Si/SiGe heterostructures of the highest quality for Si spin qubits
- process development and characterization of suitable gate oxides
- transport measurements at cryogenic temperatures (1.5K)
- manufacturing of nanostructured components
- structured Co micro magnets











- **†reactive ion etched Co for micromagnets**
- method development for determination of interface defect density at cryogenic temperatures
- extension of the characterization possibilities: whole wafers at 2 K and chips by 100 mK

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Parts of this work originate from the QUASAR project "Semiconductor quantum processor with shuttling-based scalable architecture"

